

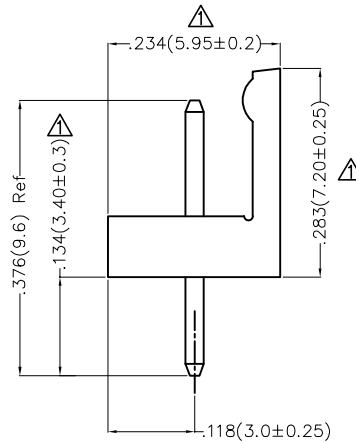
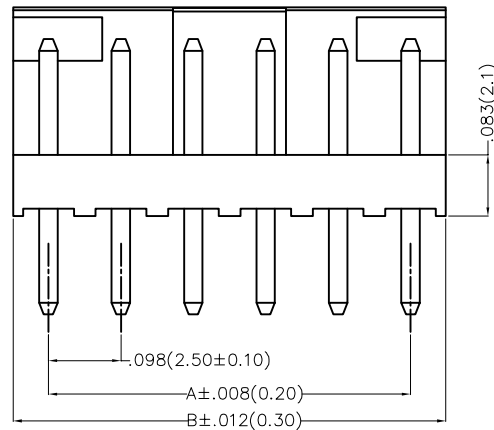
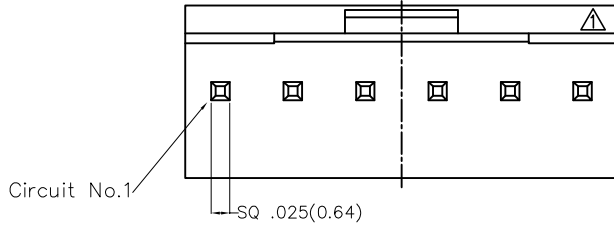
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Update structure and dimensions	25/SEP/24	MATT	LEO

Electrical

Current Rating: 3.0A AC(rms)/DC
 Voltage Rating: 250V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 1000V AC r.m.s
 Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-0)
 Contact Pin: Brass
 Plating: Tin Plated
 Mates With(Housing): FHG25020 Series

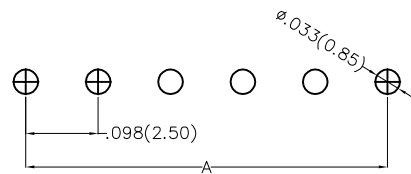


Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF25014-S02S22C1B	.098(2.50)	.197(5.00)
3	FWF25014-S03S22C1B	.197(5.00)	.295(7.50)
4	FWF25014-S04S22C1B	.295(7.50)	.394(10.00)
5	FWF25014-S05S22C1B	.394(10.00)	.492(12.50)
6	FWF25014-S06S22C1B	.492(12.50)	.591(15.00)
7	FWF25014-S07S22C1B	.591(15.00)	.689(17.50)
8	FWF25014-S08S22C1B	.689(17.50)	.787(20.00)
9	FWF25014-S09S22C1B	.787(20.00)	.886(22.50)
10	FWF25014-S10S22C1B	.886(22.50)	.984(25.00)

Ordering Information

FWF 250 14 - S XX S 2 2 C1 B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 250-Pitch2.5mm	3 Distinction No. 14	4 Row Option Single Row	5 Circuits XX	6 Entry Angle S-180° Vertical
7 Plating 2-Tin Plated	8 Material-Resin 2-PA66	9 Color-Resin C1-Brown	10 Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/JUL/13	PART NO. FWF25014-SXXS22C1B	ITEM NO. FWF25014	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X'±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY JACOB	DATE 01/JUL/13	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4		DRAWN BY CHERRY	DATE 01/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		